

SN54AC241, SN74AC241 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCAS513E – JUNE 1995 – REVISED OCTOBER 2003

- 2-V to 6-V V_{CC} Operation
- Inputs Accept Voltages to 6 V
- Max t_{pd} of 7.5 ns at 5 V

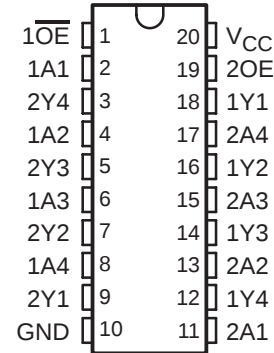
description/ordering information

These octal buffers and line drivers are designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

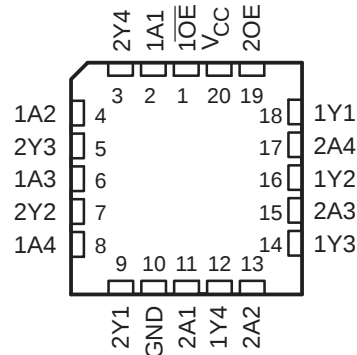
The 'AC241 devices are organized as two 4-bit buffers/drivers with separate complementary output-enable ($1OE$ and $2OE$) inputs. When $1OE$ is low or $2OE$ is high, the device passes noninverted data from the A inputs to the Y outputs. When $1OE$ is high or $2OE$ is low, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, OE should be tied to V_{CC} through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking or the current-sourcing capability of the driver.

SN54AC241 . . . J OR W PACKAGE SN54AC241 . . . DB, DW, N, NS, OR PW PACKAGE (TOP VIEW)



SN54AC241 . . . FK PACKAGE (TOP VIEW)



ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube	SN74AC241N	SN74AC241N
	SOIC – DW	Tube	SN74AC241DW	AC241
		Tape and reel	SN74AC241DWR	
	SOP – NS	Tape and reel	SN74AC241NSR	AC241
	SSOP – DB	Tape and reel	SN74AC241DBR	AC241
	TSSOP – PW	Tube	SN74AC241PW	AC241
Tape and reel		SN74AC241PWR		
-55°C to 125°C	CDIP – J	Tube	SNJ54AC241J	SNJ54AC241J
	CFP – W	Tube	SNJ54AC241W	SNJ54AC241W
	LCCC – FK	Tube	SNJ54AC241FK	SNJ54AC241FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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**TEXAS
INSTRUMENTS**

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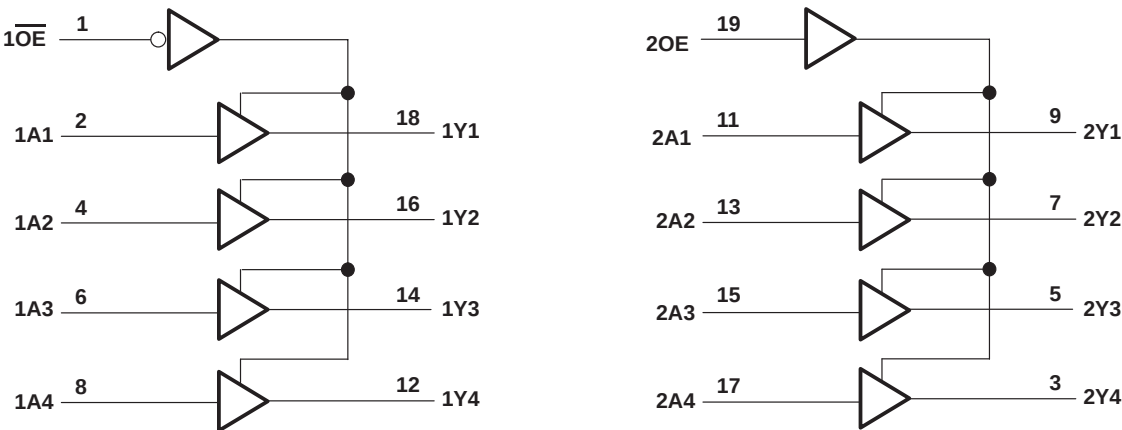
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FUNCTION TABLES

INPUTS		OUTPUT 1Y
1OE	1A	
L	H	H
L	L	L
H	X	Z

INPUTS		OUTPUT 2Y
2OE	2A	
H	H	H
H	L	L
L	X	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V_{CC} or GND	±200 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DB package	70°C/W
DW package	58°C/W
N package	69°C/W
NS package	60°C/W
PW package	83°C/W

Storage temperature range, T_{stg}	–65°C to 150°C
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[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

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recommended operating conditions (see Note 3)

			SN54AC241		SN74AC241		UNIT
			MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage		2	6	2	6	V
V _{IH}	High-level input voltage	V _{CC} = 3 V	2.1		2.1		V
		V _{CC} = 4.5 V	3.15		3.15		
		V _{CC} = 5.5 V	3.85		3.85		
V _{IL}	Low-level input voltage	V _{CC} = 3 V		0.9		0.9	V
		V _{CC} = 4.5 V		1.35		1.35	
		V _{CC} = 5.5 V		1.65		1.65	
V _I	Input voltage		0	V _{CC}	0	V _{CC}	V
V _O	Output voltage		0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 3 V		-12		-12	mA
		V _{CC} = 4.5 V		-24		-24	
		V _{CC} = 5.5 V		-24		-24	
I _{OL}	Low-level output current	V _{CC} = 3 V		12		12	mA
		V _{CC} = 4.5 V		24		24	
		V _{CC} = 5.5 V		24		24	
Δt/Δv	Input transition rise or fall rate			8		8	ns/V
T _A	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54AC241, SN74AC241

OCTAL BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AC241		SN74AC241		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 µA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I _{OH} = -12 mA	3 V	2.56			2.4		2.46		
		4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I _{OH} = -50 mA [†]	5.5 V				3.85				
	I _{OH} = -75 mA [†]	5.5 V						3.85		
V _{OL}	I _{OL} = 50 µA	3 V			0.1		0.1		0.1	V
		4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
	I _{OL} = 12 mA	3 V			0.36		0.5		0.44	
		4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I _{OL} = 50 mA [†]	5.5 V					1.65			
	I _{OL} = 75 mA [†]	5.5 V							1.65	
I _I	Data inputs	V _I = V _{CC} or GND			±0.1		±1		±1	µA
	Control inputs	V _I = V _{CC} or GND			±0.1		±1		±1	
I _{OZ}	V _O = V _{CC} or GND, V _{I(OE)} = V _{IL} or V _{IH}	5.5 V			±0.25		±5		±2.5	µA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			4		80		40	µA
C _i	V _I = V _{CC} or GND	5 V			2.5					pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range,
V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C			SN54AC241		SN74AC241		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	1.5	6	9	1	12	1.5	10	ns
t _{PHL}			1.5	6	9	1	11.5	1	10.5	
t _{PZH}	$\overline{\text{OE}}$ or OE	Y	1.5	6.5	12.5	1	13	1	13	ns
t _{PZL}			1.5	7	12	1	13	1.5	13	
t _{PHZ}	$\overline{\text{OE}}$ or OE	Y	2	8	12	1	13	2	12.5	ns
t _{PLZ}			1.5	7	12.5	1	13	1	13.5	

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



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PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C			SN54AC241		SN74AC241		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	1.5	5	7	1	9.5	1	7.5	ns
t _{PHL}			1.5	4.5	7	1	9	1	7.5	
t _{PZH}	$\overline{\text{OE}}$ or OE	Y	1.5	5.5	9	1	10	1	9.5	ns
t _{PZL}			1.5	5.5	9	1	10	1	9.5	
t _{PHZ}	$\overline{\text{OE}}$ or OE	Y	1.5	6.5	10	1	11.5	1	10.5	ns
t _{PLZ}			1.5	6	10	1	11.5	1	10.5	

PARAMETER		TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per buffer/driver	C _L = 50 pF, f = 1 MHz	45	pF

From Output Under Test

$C_L = 50 \text{ pF}$
(see Note A)

500Ω

500Ω

S1

$2 \times V_{CC}$
○ Open

TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	2 × V _{CC}
t _{PHZ} /t _{PZH}	Open

The diagram shows two waveforms: Input and Output. The Input signal is a square wave that transitions from 0V to 50% V_{CC} and back to 0V. The Output signal is a square wave that transitions from V_{OL} to V_{OH} and back to V_{OL} . The propagation delay t_{PLH} is the time from the input crossing 50% V_{CC} to the output crossing 50% V_{CC} . The propagation delay t_{PHL} is the time from the input crossing 50% V_{CC} to the output crossing 50% V_{CC} .

Output Control (low-level enabling) V_{CC} 0 V

Waveform 1 $\approx V_{CC}$ V_{OL}

Waveform 2 V_{OH} $\approx 0\text{ V}$

Timing parameters: t_{PZL} , t_{PLZ} , t_{PZH} , t_{PHZ}

Voltage levels: $50\% V_{CC}$, $V_{OL} + 0.3\text{ V}$, $V_{OH} - 0.3\text{ V}$

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AC241DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74AC241DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC241DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC241DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC241DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC241DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC241DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC241N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AC241NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AC241NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC241NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC241PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC241PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC241PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI
SN74AC241PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC241PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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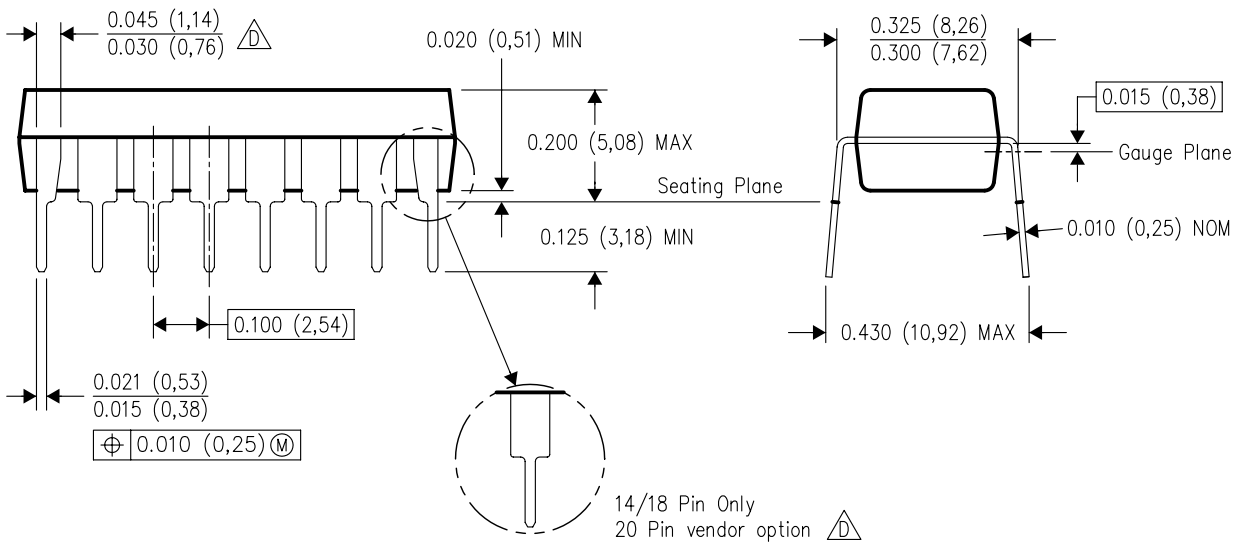
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD

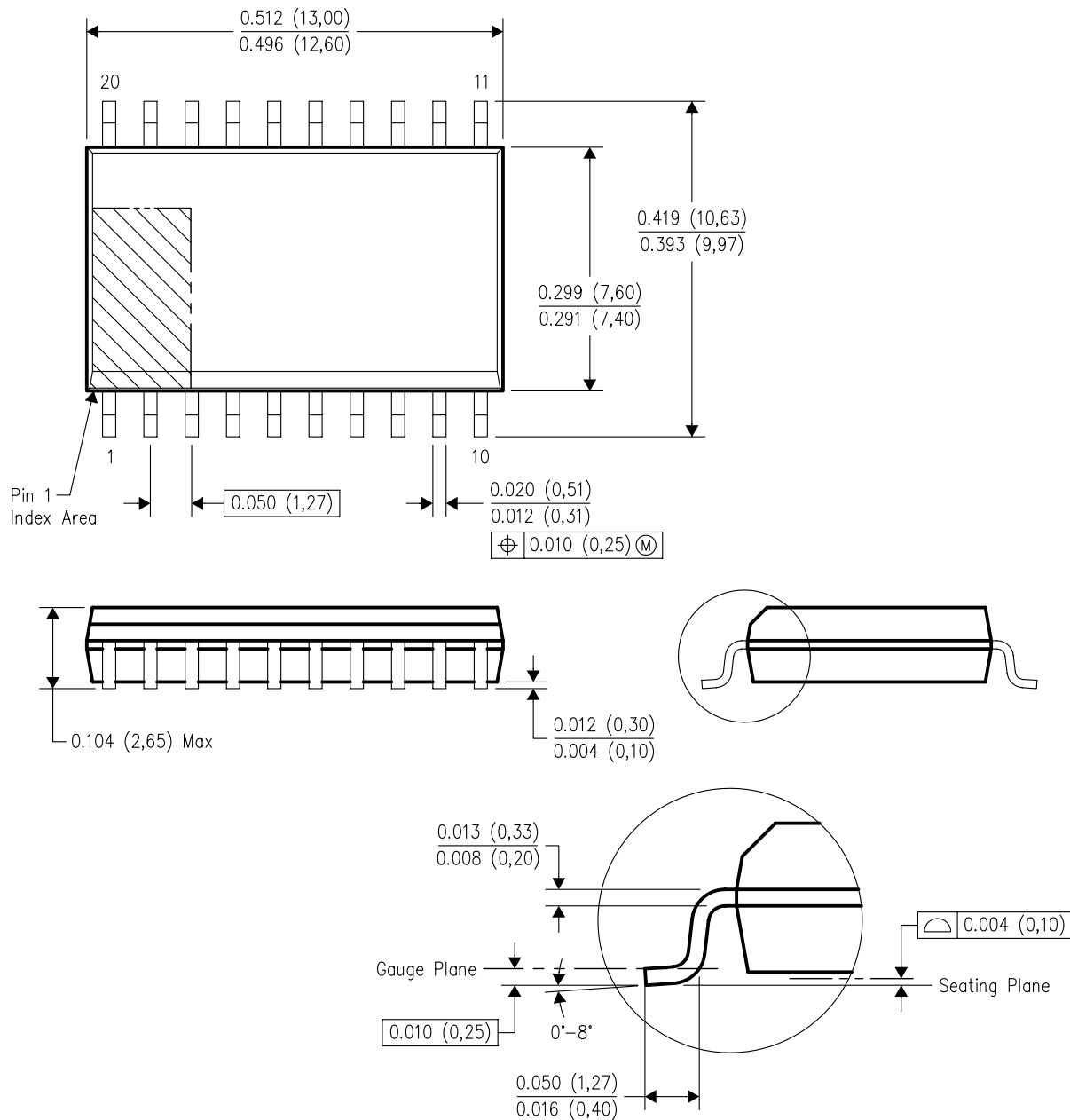


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- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



4040000-4/F 06/2004

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-013 variation AC.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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